

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-4. (Canceled)

5. (Currently amended) A method for producing a solar cell module comprising:

~~a step for~~ providing a plurality of solar cell elements each having a front surface electrode formed on a light-receiving surface of a semiconductor substrate thereof, and a back surface electrode formed on a non-light receiving surface of the semiconductor substrate;

~~a step for~~ connecting a first ~~connection tab and inner lead to~~ the front surface electrode of one of the solar cell elements, by melting a first solder layer that is disposed therebetween, wherein the first inner lead comprises a metal foil;

~~a step for~~ connecting a second ~~connection tab and inner lead to~~ the back surface electrode of another of the solar cell elements, by melting a second solder layer that is disposed therebetween and has a different melting point than the first solder layer, wherein the second inner lead comprises a metal foil; and

~~a step for~~ connecting the first ~~connection tab and inner lead to~~ the second ~~connection tab inner lead~~.

6. (Previously presented) The method for producing a solar cell module according to claim 5, wherein the first solder layer has a higher melting point than the second solder layer.

7. (Previously presented) The method for producing a solar cell module according to claim 6, wherein the first solder layer is substantially free of lead.

8. (Currently amended) The method for producing a solar cell module according to claim 5, wherein the first or the second connection-tab inner lead is provided with a through hole at a connection area between the ~~connection-tab~~ inner lead and the front surface electrode or the back surface electrode.

9. (Currently amended) The method for producing a solar cell module according to claim 5, wherein the ~~connection-tabs~~ inner leads are connected to a common connection line by means of a solder, and the ~~connection-tabs~~ inner leads are provided with through holes at connection areas between the ~~connection-tabs~~ inner leads and the common connection line.

10. (Currently amended) The method for producing a solar cell module according to claim 5, wherein the ~~connection-tabs~~ inner leads are connected to a common connection line by means of a solder, and the common connection line is provided with through holes at connection areas between the common connection line and the ~~connection-tabs~~ inner leads.

11. (Previously presented) The method for producing a solar cell module according to claim 5, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the output wires are provided with through holes at connection areas between the output wires and the terminals.

12. (Previously presented) The method for producing a solar cell module according to claim 5, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the terminals are provided with through holes at connection areas between the terminals and the output wires.

13-22. (Canceled)

23. (Currently amended) The method for producing a solar cell module according to claim 5, further comprising coating a surface of the electrode with the solder layer before ~~the step for~~ connecting a first ~~connection-tab~~ inner lead to the front surface electrode of one of the solar cell elements, through a first solder layer; ~~the step for~~ connecting a second ~~connection-tab~~ inner lead to the back surface electrode of another of the solar cell elements, through a second solder layer having a different melting point than the first solder layer; and ~~the step for~~ connecting the first ~~connection-tab~~ inner lead to the second ~~connection-tab~~ inner lead.

24. (Currently amended) The method for producing a solar cell module according to claim 5, further comprising coating a surface of the ~~connection-tab~~ inner lead with the solder layer before ~~the step for~~ connecting a first ~~connection-tab~~ inner lead to the front surface electrode of one of the solar cell elements, through a first solder layer; ~~the step for~~ connecting a second ~~connection-tab~~ inner lead to the back surface electrode of another of the solar cell elements, through a second solder layer having a different melting point than the first solder layer; and ~~the step for~~ connecting the first ~~connection-tab~~ inner lead to the second ~~connection-tab~~ inner lead.

25. (Currently amended) A method for producing a solar cell module, comprising:

~~a step for~~ providing a solar cell element having a front surface electrode formed on a light-receiving surface of a semiconductor substrate thereof, and a back surface electrode formed on a non-light receiving surface of the semiconductor substrate;

~~a step for~~ connecting a first ~~connection-tab and~~ inner lead to the front surface electrode or the back surface electrode of the solar cell element, by melting a first solder layer that is disposed therebetween, wherein the first inner lead comprises a metal foil; and

~~a step for~~ connecting a second ~~connection-tab and~~ inner lead to an electrode of the solar cell element to which the first ~~connection-tab~~ inner lead is not connected, by melting the second solder layer that is disposed therebetween and has a lower melting point than the first solder layer, after performing the above ~~step for~~ connecting the first ~~connection-tab~~ inner lead, wherein the second inner lead comprises a metal foil.

26. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the first solder layer is substantially free of lead.

27. (Currently amended) The method for producing a solar cell module according to claim 25, wherein the first or the second ~~connection-tab~~ inner lead is provided with a through hole at a connection area between the ~~connection-tab~~ inner lead and the front surface electrode or the back surface electrode.

28. (Currently amended) The method for producing a solar cell module according to claim 25, wherein the ~~connection-tabs~~ inner leads are connected to a common connection line by means of a solder, and the ~~connection-tabs~~ inner leads are provided with through holes at connection areas between the ~~connection-tabs~~ inner leads and the common connection line.

29. (Currently amended) The method for producing a solar cell module according to claim 25, wherein the ~~connection-tabs~~ inner leads are connected to a common connection line by means of a solder, and the common connection line is provided with through holes at connection areas between the common connection line and the ~~connection-tabs~~ inner leads.

30. (Previously presented) The method for producing a solar cell module according to claim 25, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the output wires are provided with through holes at connection areas between the output wires and the terminals.

31. (Previously presented) The method for producing a solar cell module according to claim 25, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the terminals are provided with through holes at connection areas between the terminals and the output wires.

32. (Currently amended) The method for producing a solar cell module according to claim 25, further comprising coating a surface of the electrode with the solder layer before ~~the step for~~ connecting a first connection tab to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and ~~the step for~~ connecting a second ~~connection-tab~~ inner lead to an electrode of the solar cell element to which the first ~~connection-tab~~ inner lead is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above ~~step for~~ connecting the first ~~connection-tab~~ inner lead.

33. (Currently amended) The method for producing a solar cell module according to claim 25, further comprising coating a surface of the ~~connection-tab~~ inner lead with the solder layer before ~~the step for~~ connecting a first ~~connection-tab~~ inner lead to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and ~~the step for~~ connecting a second ~~connection-tab~~ inner lead to an electrode of the solar cell element to which the first ~~connection-tab~~ inner lead is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above ~~step for~~ connecting the first ~~connection-tab~~ inner lead.